L	Hits	Search Text	DB	Time stamp
Number 1	14	(phonoleulfonia popula anid) and (	Van 3 m	
		<pre>(phenolsulfonic near2 acid) and (cmp or chemical near2 mechanical near2 (planar\$8 or polish\$7))</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/09/15 14:21
2	2705	(molybdenum) and (cmp or chemical near2 mechanical near2 (planar\$8 or polish\$7))	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/09/15 14:21
3	16	<pre>(molybdenum near10 salt) and (cmp or chemical near2 mechanical near2 (planar\$8 or polish\$7))</pre>	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/09/15 14:27
4	33	copper near2 sulfate same slurry and (chemical near2 mechanical near2 (planariz\$5 or polish\$6))	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/09/15 14:29
5	470404	copper near2 sulfate or "cuso.sub.4" or edta or "feno.sub.3" ferric near2 nitrate or iron near2 nitrate or koh or potassium near2 hydroxide or "k.sub.2s.ub.2o.sub.8" or naoh or sodium near2 hydroxide or sodium near2 nitride or ammonium near2 hydroxide	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/15 14:33
6	1765	(copper near2 sulfate or "cuso.sub.4" or edta or "feno.sub.3" ferric near2 nitrate or iron near2 nitrate or koh or potassium near2 hydroxide or "k.sub.2s.ub.2o.sub.8" or naoh or sodium near2 hydroxide or sodium near2 nitride or ammonium near2 hydroxide) same (cmp or chemical near2 mechanical near2 (planar\$7 or polish\$7))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/15 14:35
7	763	(copper near2 sulfate or "cuso.sub.4" or edta or "feno.sub.3" ferric near2 nitrate or iron near2 nitrate or koh or potassium near2 hydroxide or "k.sub.2s.ub.2o.sub.8" or naoh or sodium near2 hydroxide or sodium near2 nitride or ammonium near2 hydroxide) near10 slurr\$6 same (cmp or chemical near2 mechanical near2 (planar\$7 or polish\$7))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/15 14:35
8		(copper near2 sulfate or "cuso.sub.4" or edta or "feno.sub.3" ferric near2 nitrate or iron near2 nitrate or koh or potassium near2 hydroxide or "k.sub.2s.ub.2o.sub.8" or naoh or sodium near2 hydroxide or sodium near2 nitride or ammonium near2 hydroxide) near10 slurr\$6 near5 additiv\$6 same (cmp or chemical near2 mechanical	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/15 14:37
9	16	near2 (planar\$7 or polish\$7)) (copper near2 sulfate or "cuso.sub.4" or edta or "feno.sub.3" ferric near2 nitrate or iron near2 nitrate or koh or potassium near2 hydroxide or "k.sub.2s.ub.2o.sub.8" or naoh or sodium near2 hydroxide or sodium near2 nitride or ammonium near2 hydroxide) near10 slurr\$6 same (cmp or	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/15 15:54
10	0	chemical near2 mechanical near2 (planar\$7 or polish\$7)) same copper near2 layer (cucl or copper near2 chloride or iron near2 chloride or fecl near2 chloride or fecl sub.3") near10 slurr\$6 same (cmp or chemical near2 mechanical near2 (planar\$7 or religible\$7.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/15 15:54

11	3	The second of the second secon	USPAT;	2004/09/15	丁
		near2 chloride or ferric near2 chloride	US-PGPUB;	15:55	- 1
		or fecl or "fecl.sub.3") same (cmp or	EPO; JPO;		-
	i i	chemical near2 mechanical near2 (planar\$7	DERWENT;		ŀ
12		or polish\$7)) same copper near2 layer	IBM_TDB		
12	44		USPAT;	2004/09/15	- 1
	9	near2 chloride or ferric near2 chloride	US-PGPUB;	16:36	- 1
		or fecl or "fecl.sub.3") same (cmp or	EPO; JPO;		- 1
		chemical near2 mechanical near2 (planar\$7 or polish\$7))			- 1
13	2	1 • ' ' '	IBM_TDB		
10		6562512.pm.	USPAT;	2004/09/15	ł
			US-PGPUB;	16:36	- [
			EPO; JPO; DERWENT;		
			IBM TDB		1
_	135	single near2 step near5 slurry	USPAT;	2004/09/13	
	İ	J	US-PGPUB;	11:52	- 1
			EPO; JPO;	111.32	
			DERWENT;		-
1			IBM TDB	1	
-	11		USPAT;	2004/09/13	
1		(copper near2 tantalum or cu\$1ta)	US-PGPUB;	12:00	
	1		EPO; JPO;		-
			DERWENT;		
			IBM_TDB		ı
_	17	i J	USPAT;	2004/09/13	
İ		(copper same tantalum or cu\$1ta)	US-PGPUB;	13:35	
			EPO; JPO;		1
	İ		DERWENT;		
_	79	single nears glunny and /nears	IBM_TDB		
	'3	single near5 slurry and (copper same tantalum or cu\$1ta)	USPAT;	2004/09/13	
		cancalum of cupica,	US-PGPUB;	13:35	
			EPO; JPO;		
			DERWENT; IBM TDB		
-	83	single near5 slurry and (copper same	USPAT;	2004/09/13	
		(tantalum or cu\$1ta or tan or ta))	US-PGPUB;	13:35	1
		, , , , , , , , , , , , , , , , , , , ,	EPO; JPO;	13.33	
			DERWENT;		
			IBM TDB		
-	55	single near5 slurry and (copper same	USPAT;	2004/09/13	
		(tantalum or cu\$1ta or tan or ta)) and	US-PGPUB;	13:37	
		(peorxide or sulfuric or ntric or acetic	EPO; JPO;		1
		or phosphoric)	DERWENT;		ŀ
	0.0		IBM_TDB		
_	86	banke (peroxide or	USPAT;	2004/09/13	
		sulfuric or ntric or acetic or phosphoric	US-PGPUB;	13:38	1
		or "h.sub.2o.sub.2" or "h.sub.3po.sub.4" or "h.sub.2so.sub.4" or "hno.sub.3")	EPO; JPO;		
		or mo.sub.3")	DERWENT;		
<b>-</b>	17	single near5 slurry same (peroxide or	IBM_TDB	2004/00/12	
	-'	sulfuric or ntric or acetic or phosphoric	USPAT;	2004/09/13	
		or "h.sub.20.sub.2" or "h.sub.3po.sub.4"	US-PGPUB; EPO; JPO;	13:43	
		or "h.sub.2so.sub.4" or "hno.sub.3") and	DERWENT;		1
		((cu copper) same (tantalum or ta or	IBM TDB		
		tan))			
-	2	6063306.pn.	USPAT;	2004/09/13	
			US-PGPUB;	14:01	İ
			EPO; JPO;		
	*		DERWENT;		
		000000	IBM_TDB		
_	2	20020020833.pn.	USPĀT;	2004/09/13	
		ļ	US-PGPUB;	14:13	
			EPO; JPO;		
	]	1	DERWENT;		
_	841	(copper or gu) norm10 // : 3	IBM_TDB		
	""	(copper or cu) near10 (tantalum or ta or tan) same planar\$8	USPAT;	2004/09/13	
		can' same branatso	US-PGPUB;	14:14	
			EPO; JPO;		İ
			DERWENT; IBM TDB		
			TOLI IND	_	1

_	172	(copper or cu) near10 (tantalum or ta or tan) near10 planar\$8	USPAT; US-PGPUB; EPO; JPO;	2004/09/13 14:48
			DERWENT; IBM TDB	
-	16	((copper or cu) near10 (tantalum or ta or tan) near10 planar\$8) and (single near2		2004/09/13
-		step) same (slurry or solution)	EPO; JPO;	111.24
	2	5447887.pn.	DERWENT; IBM_TDB	
		3447007.pn.	USPAT; US-PGPUB;	2004/09/13 14:24
			EPO; JPO; DERWENT;	
-	48	(FF ) (carroutant of ca of	IBM_TDB USPAT;	2004/09/13
		tan) near10 planar\$8 same select\$8	US-PGPUB; EPO; JPO;	14:49
			DERWENT; IBM TDB	
-	38	(copper or cu) near10 (tantalum or ta or tan) near10 planar\$8 same selectiv\$8	USPAT;	2004/09/13
		can/ hearto pranaryo same serectivao	US-PGPUB; EPO; JPO;	14:59
	100	,	DERWENT; IBM_TDB	
_	123	tan) and (single or one near2 step)	USPAT; US-PGPUB;	2004/09/13 15:05
		near10 slurry	EPO; JPO; DERWENT;	
_	2	5954997.pn.	IBM_TDB USPAT;	2004/09/14
			US-PGPUB; EPO; JPO;	10:43
			DERWENT;	is a second
_	6	(cmp or chemical adj mechanical adj	IBM_TDB USPAT;	2004/09/14
		planar\$) and abrasive near2 particle near10 coating near10 ("ceo.sub.2" or	US-PGPUB; EPO; JPO;	10:46
		cerium near2 oxide or ceo2)	DERWENT; IBM_TDB	
-	2	near10 ("ceo.sub.2" or cerium near2 oxide	USPAT; US-PGPUB;	2004/09/14
		or ceo2)	EPO; JPO; DERWENT;	
_	14	abrasive near2 particle near10	IBM_TDB USPAT;	2004/09/14
		("ceo.sub.2" or cerium near2 oxide or ceo2) near10 (coat\$5)	US-PGPUB; EPO; JPO;	11:02
		, (33,43)	DERWENT; IBM TDB	
_	8	abrasive near2 particle same sol near2 method and cmp	USPAT; US-PGPUB;	2004/09/14
		metrica ara emp	EPO; JPO;	10:58
_	5	/"/50057/" #5004711# #5000/05#\	DERWENT; IBM_TDB	
	3	("4588576" "5004711" "5238625").pn. and sol	USPAT; US-PGPUB;	2004/09/14   10:56
			EPO; JPO; DERWENT;	
-	39	abrasive near2 particle same sol and cmp	<pre>IBM_TDB USPAT;</pre>	2004/09/14
		-	US-PGPUB; EPO; JPO;	10:58
			DERWENT; IBM TDB	
_	421	abrasive near2 particle near10 ("ceo.sub.2" or cerium near2 oxide or	USPAT; US-PGPUB;	2004/09/14 11:02
		ceo2)	EPO; JPO; DERWENT;	. 11.02
			IBM TDB	

_	17	Far or or or incarro	USPAT;	2004/09/14	
		("ceo.sub.2" or cerium near2 oxide or	US-PGPUB;	11:09	
		ceo2) near10 (coat\$5 or cover\$5)	EPO; JPO;		
			DERWENT;		
	2702		IBM_TDB		
~	2703	Paratore mearing (coate) of		2004/09/14	
		cover\$5)	US-PGPUB;	11:11	
			EPO; JPO;	1	
ŀ			DERWENT;		ĺ
	2635		IBM_TDB	1	
-	2033			2004/09/14	
		cover\$5) near2 particle	US-PGPUB;	11:13	ŀ
i			EPO; JPO;		
			DERWENT;		
1 -	8	abrasive near2 particle near10 (coat\$5 or	IBM_TDB	2004/20/24	ı
		cover\$5) near2 particle near10 (coat\$5 or		2004/09/14	- 1
		("sio.sub.2" or "alo.sub.2")	US-PGPUB;	11:11	ı
1		( 510.5db.2 01 a10.5db.2 )	EPO; JPO;		
			DERWENT;		
_	202	(abrasive near2 particle near10 (coat\$5	IBM_TDB USPAT;	2004/09/14	- [
	1	or cover\$5) near2 particle) and cmp	US-PGPUB;	11:12	
		parato, and emp	EPO; JPO;	11:12	1
	1		DERWENT;		
			IBM TDB		
-	11		USPAT;	2004/09/14	- [
		or cover\$5) near2 particle) and cmp) and	US-PGPUB;	11:12	
	1	@py<1999	EPO; JPO;	1	
			DERWENT;		
			IBM TDB	1	
-	2365		USPAT;	2004/09/14	
		near2 particle	US-PGPUB;	11:13	
			EPO; JPO;	1	ł
			DERWENT;		
	142		IBM_TDB	İ	
<u> </u>	141		USPAT;	2004/09/14	-
		near2 particle) and cmp	US-PGPUB;	11:13	
			EPO; JPO;		ı
			DERWENT;		i
l _	10	(/abraging noan) martials were 10 /	IBM_TDB		
	1	((abrasive near2 particle near10 (coat\$5) near2 particle) and cmp) and Cpy<2000	USPAT;	2004/09/14	1
1		means parefere, and emp, and epy<2000	US-PGPUB;	11:58	
			EPO; JPO;		Ī
			DERWENT;	1	1
-	1139	(cu near2 (ta or tan) or copper near4	IBM_TDB	2004/00/14	
		tantalum) same (polish\$5 or planar\$7 or	USPAT; US-PGPUB;	2004/09/14	ı
	İ	cmp)	EPO; JPO;	11:59	
	1	* '	DERWENT;		
	1		IBM TDB		
_	1		USPAT;	2004/09/14	
		tantalum) same (polish\$5 or planar\$7 or	US-PGPUB;	12:00	1
	1	cmp) and slurry same (fecl cucl	EPO; JPO;		
		"fecl.sub.3" or iron near2 chloride or	DERWENT;		
		copper near2 chloride)	IBM TDB		1
_	4383	slurry same metal near2 salt	USPAT;	2004/09/14	
	İ		US-PGPUB;	13:25	
			EPO; JPO;		1
			DERWENT;		
_	16400	I mannan au mul a 12 d	IBM_TDB		
	16422	(copper or cu) near10 (cmp or polish\$5 or	USPAT;	2004/09/14	
		planar\$8) slurry same metal near2 salt	US-PGPUB;	13:26	1
	]		EPO; JPO;		1
			DERWENT;		
_	79	(copper or cu) poar10 /	IBM_TDB		1
	'3	<pre>(copper or cu) near10 (cmp or polish\$5 or planar\$8) and slurry same metal near2</pre>	USPAT;	2004/09/14	1
		salt	US-PGPUB;	13:26	
		···	EPO; JPO;		1
	]		DERWENT; IBM TDB		
			TOLLIDO		1

-	5	(copper or cu) near10 (cmp or polish\$5 or planar\$8) and slurry same ("fecl" or		2004/09/14	
		"fecl.sub.3" or "cucl.sub.2")	US-PGPUB; EPO; JPO;	13:28	
		,	DERWENT;		
İ	201		IBM_TDB		
-	291	slurry same ("fecl" or "fecl.sub.3" or "cucl.sub.2")	USPAT;	2004/09/14	
[		cuci.sub.2")	US-PGPUB;	13:28	
			EPO; JPO; DERWENT;		
			IBM TDB		- 1
-	54		USPAT;	2004/09/14	
		"cucl.sub.2") same (copper or cu)	US-PGPUB;	13:29	ı
			EPO; JPO;		
			DERWENT; IBM TDB		1
-	8	Termer   rect of rect. 3db. 5 of	USPAT;	2004/09/14	
		"cucl.sub.2") same (polish\$5 or planar\$8)	US-PGPUB;	13:29	
1			EPO; JPO;		
1	İ		DERWENT; IBM TDB		1
-	21		USPAT;	2004/09/14	
		"cucl.sub.2") same (additiv\$5 or	US-PGPUB;	13:30	
		stabiliz\$5)	EPO; JPO;		
			DERWENT;		ĺ
-	17	slurry same ("fecl" or "fecl.sub.3" or	IBM_TDB USPAT;	2004/09/14	
		"cucl.sub.2") and (cmp or chemical near2	US-PGPUB;	13:32	
		mechanical)	EPO; JPO;		1
			DERWENT;		
_	24	slurry same (ferric near2 chloride) and	IBM_TDB	2004/00/14	
		(cmp or chemical near2 mechanical)	USPAT; US-PGPUB;	2004/09/14	
			EPO; JPO;	13.43	
			DERWENT;		1
1-	31	slurry same (copper near2 sulfate or	IBM_TDB		
		"cuso.sub.4") and (cmp or chemical near2	USPAT; US-PGPUB;	2004/09/14	
		mechanical) near10 (copper or cu)	EPO; JPO;	13.30	
		•	DERWENT;		
_	104	clumnic come (bab) 1 /	IBM_TDB		
	104	slurry same (koh) and (cmp or chemical near2 mechanical) near10 (copper or cu)	USPAT;	2004/09/14	
			US-PGPUB; EPO; JPO;	13:54	1
			DERWENT;		
_	0	(mollabedomana area of the control o	IBM_TDB		
	"	(molybdenum near2 salt or phenolsulfonic near2 acid) same slurry and (cmp or	USPAT;	2004/09/14	
		chemical near2 mechanical)	US-PGPUB; EPO; JPO;	13:55	
		,,	DERWENT;		
_	21	/mh.au	IBM_TDB		
-	31	(phenolsulfonic near2 acid) and (cmp or chemical near2 mechanical)	USPAT;	2004/09/14	
		medianical)	US-PGPUB; EPO; JPO;	14:45	
			DERWENT;		
	12055		IBM TDB		
_	43066	organic near2 acid near10 acetic	USPAT;	2004/09/14	
			US-PGPUB;	14:46	
			EPO; JPO; DERWENT;		
	10505		IBM TDB		
_	18797	(organic near2 acid near10 acetic) and	USPAT;	2004/09/14	
		@py<1995	US-PGPUB;	14:46	
			EPO; JPO; DERWENT;		
	] [		IBM TDB		
-	25590	organic near2 acid near2 acetic	USPAT;	2004/09/14	
			US-PGPUB;	14:47	
			EPO; JPO;		
	<u> </u>		DERWENT; IBM TDB		
					1

-	228	organic near2 acid near2 acetic and cmp	USPAT;	2004/09/14	
		-	US-PGPUB;	14:47	
			EPO; JPO;	1	- 1
			DERWENT;		ĺ
			IBM TDB		
-	13		USPAT;	2004/09/14	ı
	c -	and @py<1998	US-PGPUB;	14:48	ı
			EPO; JPO;		Ī
			DERWENT;		
			IBM TDB		
-	304	Partition banks but hears	USPĀT;	2004/09/14	
		method	US-PGPUB;	14:48	-
			EPO; JPO;		
İ			DERWENT;		- 1
			IBM TDB		
-	211	Farance Model o Bot Mediz	USPAT;	2004/09/14	-
		method	US-PGPUB;	14:48	
	-		EPO; JPO;		
1			DERWENT;		-
			IBM TDB	1	
-	67		USPAT;	2004/09/14	
1	1	method) and @py<1999	US-PGPUB;	14:49	
İ			EPO; JPO;		- 1
			DERWENT;		
i			IBM TDB		İ
-	19	sol same solgel near10 method	USPAT;	2004/09/14	- 1
			US-PGPUB;	14:50	ı
	İ		EPO; JPO;		
			DERWENT;	1	
			IBM TDB		
-	7824	sol near2 method	USPAT;	2004/09/14	
			US-PGPUB;	14:50	-
			EPO; JPO;		
			DERWENT;		
			IBM TDB		
-	30	mossion banks abrabive nearz	USPAT;	2004/09/14	
		particle	US-PGPUB;	14:52	
			EPO; JPO;		
			DERWENT;		ı
			IBM TDB		
-	298	sol adj method	USPĀT;	2004/09/14	1
			US-PGPUB;	14:53	
			EPO; JPO;	]	
			DERWENT;		
			IBM TDB		
-	221	sol adj method and particle	USPAT;	2004/09/14	ı
	İ		US-PGPUB;	14:53	
	1		EPO; JPO;		
1			DERWENT;		
	100		IBM_TDB		
-	109	sol adj method and particle near10 oxide	USPĀT;	2004/09/14	
			US-PGPUB;	14:54	1
			EPO; JPO;		
			DERWENT;		
_	1 20		IBM_TDB		1
	20	sol adj method and particle and (cmp or	USPAT;	2004/09/14	ļ
		chemical near2 mechanical)	US-PGPUB;	15:39	
1	]		EPO; JPO;		
	1 1		DERWENT;		
i _	57	/fan naan2 akana	IBM_TDB		
	3/	(fan near2 zhang or joseph near2 levert	USPAT;	2004/09/14	1
		or daniel near2 towery).in.	US-PGPUB;	15:39	
ĺ			EPO; JPO;		
			DERWENT;		1
_	17	//fan noan? when and	IBM_TDB		
]	'/	((fan near2 zhang or joseph near2 levert	USPAT;	2004/09/14	
	] [	or daniel near2 towery).in.) and (copper near10 tantalum or cu near2 ta)	US-PGPUB;	16:00	1
		near tall (antarum of cu near ta)	EPO; JPO;		
	] [		DERWENT;		1
L			IBM TDB		1

			T T C D D M	1 2004 /00 /14
_	10097	etching near10 planar\$9	USPAT; US-PGPUB;	2004/09/14 15:53
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	233	etching near10 planar\$9 same slurry	USPAT;	2004/09/14
			US-PGPUB;	15:53
			EPO; JPO; DERWENT;	
			IBM TDB	
_	39	etching near10 planar\$9 same slurry and	USPĀT;	2004/09/14
		@py<1999	US-PGPUB;	15:53
			EPO; JPO;	
			DERWENT;	
		4044036	IBM_TDB	2004/09/14
_	2	4944836.pn.	USPAT; US-PGPUB;	16:09
			EPO; JPO;	10.03
			DERWENT;	
			IBM_TDB	
-	402	potassium near2 salt near10 koh	USPAT;	2004/09/14
			US-PGPUB;	16:09
	1		EPO; JPO;	
1	1		DERWENT; IBM TDB	
l _	0	potassium near2 salt near10 koh and cmp	USPAT;	2004/09/14
		production and and	US-PGPUB;	16:09
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	11	▲	USPAT;	2004/09/14
		slurr\$6	US-PGPUB; EPO; JPO;	16:11
		•	DERWENT;	
:			IBM TDB	
_	13060	mol same slurr\$6	USPAT;	2004/09/14
			US-PGPUB;	16:11
			EPO; JPO;	
			DERWENT;	
_	123	(mo molybdenum or phenolsulfonic) same	IBM_TDB USPAT;	2004/09/14
	125	slurr\$6 and (cmp or chemical near2	US-PGPUB;	16:12
		mechanical)	EPO; JPO;	
	1		DERWENT;	
			IBM_TDB	
_	15	(mo molybdenum or phenolsulfonic) near10	USPAT;	2004/09/14
•	1	slurr\$6 and (cmp or chemical near2   mechanical)	US-PGPUB; EPO; JPO;	16:13
1		medianical,	DERWENT;	
			IBM TDB	
-	3		USPĀT;	2004/09/14
		slurr\$6 and (cmp)	US-PGPUB;	16:13
			EPO; JPO;	
			DERWENT; IBM TDB	
_	10297	   (mo molybdenum or phenolsulfonic) and	USPAT;	2004/09/14
	10257	(cmp or chemical near2 mechanical near2	US-PGPUB;	16:14
j l		(polish\$5 or planar\$8))	EPO; JPO;	
			DERWENT;	
			IBM_TDB	0004/00/11
-	1072	(mo molybdenum or phenolsulfonic) same	USPAT;	2004/09/14
		(cmp or chemical near2 mechanical near2	US-PGPUB;	16:14
		(polish\$5 or planar\$8))	EPO; JPO; DERWENT;	
			IBM TDB	
-	201	(mo molybdenum or phenolsulfonic) same	USPAT;	2004/09/14
		(cmp or chemical near2 mechanical near2	US-PGPUB;	16:15
		(polish\$5 or planar\$8)) and @py<2000	EPO; JPO;	
			DERWENT;	
ì	i		IBM TDB	1

-	35	(molybdenum or phenolsulfonic) same (cmp	USPAT;	2004/09/14
		or chemical near2 mechanical near2	US-PGPUB;	16:21
1		(polish\$5 or planar\$8)) and @py<2000	EPO; JPO;	1
			DERWENT;	
1			IBM TDB	]
-	3001	phenolsulfonic	USPAT;	2004/09/14
			US-PGPUB;	16:21
1			EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	2931	phenolsulfonic near2 acid	USPAT;	2004/09/14
			US-PGPUB;	16:21
			EPO; JPO;	
			DERWENT;	
	10	, , , , , , , , , , , , , , , , , , , ,	IBM_TDB	
_	12	(phenolsulfonic near2 acid) and (cmp or	USPAT;	2004/09/15
		chemical near2 mechanical near2 planar\$8)	US-PGPUB;	14:19
			EPO; JPO;	
			DERWENT;	
			IBM TDB	